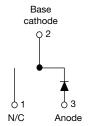
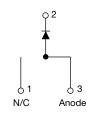


## Ultrafast Rectifier, 8 A FRED Pt®

# TO-263AB (D<sup>2</sup>PAK) TO-262AA





VS-8ETU04SHM3

VS-8ETU04-1HM3

PRODUCT SUMMARY	
Package	TO-263AB (D <sup>2</sup> PAK), TO-262AA
I <sub>F(AV)</sub>	8 A
$V_{R}$	400 V
V <sub>F</sub> at I <sub>F</sub>	0.94 V
t <sub>rr</sub> typ.	35 ns
T <sub>J</sub> max.	175 °C
Diode variation	Single die

#### **FEATURES**

- Ultrafast recovery time
- · Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C





#### **DESCRIPTION / APPLICATIONS**

Vishay Semiconductors FRED Pt® series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS					
Repetitive peak reverse voltage	$V_{RRM}$		400	V					
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 155 °C	8						
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>C</sub> = 25 °C	100	Α					
Repetitive peak forward current	I <sub>FRM</sub>		16						
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C					

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	I <sub>R</sub> = 100 μA	400	-	i	.,			
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 8 A	-	1.19	1.3	V			
Torward voitage		I <sub>F</sub> = 8 A, T <sub>J</sub> = 150 °C	-	0.94	1.0				
Reverse leakage current I <sub>R</sub>		$V_R = V_R$ rated	-	0.2	10				
		T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	20	500	μA			
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 400 V	-	14	-	pF			
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ			

## **VS-8ETU04SHM3, VS-8ETU04-1HM3**

## Vishay Semiconductors

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS			MAX.	UNITS	
		I <sub>F</sub> = 1.0 A, dI <sub>F</sub> /dt =	50 A/μs, V <sub>R</sub> = 30 V	-	35	60		
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	43	-	ns	
		T <sub>J</sub> = 125 °C		-	67	-		
Dools was a summent	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C	$I_F = 8 A$ $dI_F/dt = 200 A/\mu s$ $V_R = 200 V$	-	2.8	-	- A	
Peak recovery current		T <sub>J</sub> = 125 °C		-	6.3	-		
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	]	-	60	-	nC	
		T <sub>J</sub> = 125 °C	]	-	210	-	IIC	

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	AMETER SYMBOL TEST CONDITIONS				MAX.	UNITS			
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55	-	175	°C			
Thermal resistance, junction to case	R <sub>thJC</sub>		-	1.8	2.0				
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	50	°C/W			
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.5	-				
Waight			-	2.0	-	g			
Weight			-	0.07	-	oz.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Modeing daving		Case style TO-263AB (D <sup>2</sup> PAK) 8ET		8ETU	J04SH				
Marking device		Case style TO-262		8ETU	04-1H				

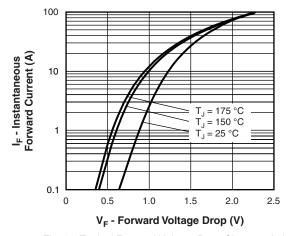


Fig. 1 - Typical Forward Voltage Drop Characteristics

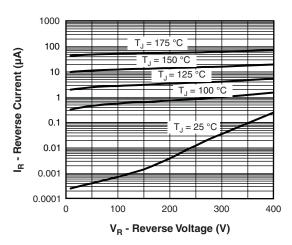


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

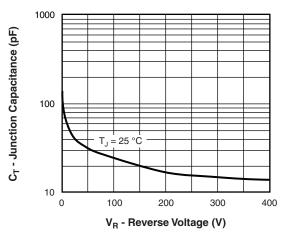


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

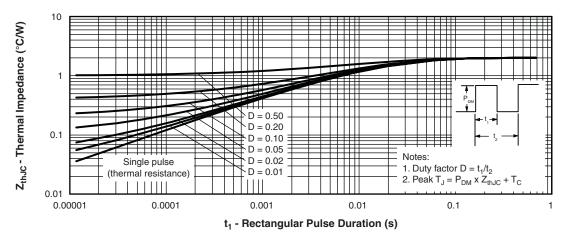


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

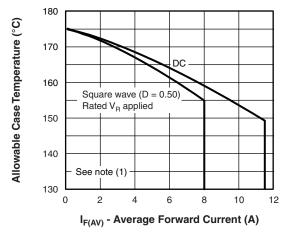


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

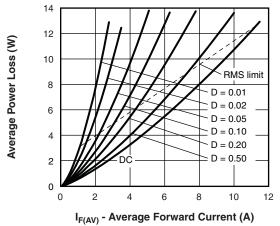


Fig. 6 - Forward Power Loss Characteristics

#### www.vishay.com

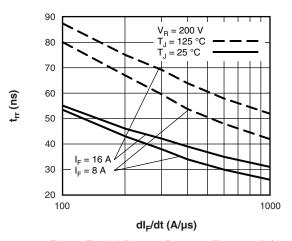


Fig. 7 - Typical Reverse Recovery Time vs.  $dI_F/dt$ 

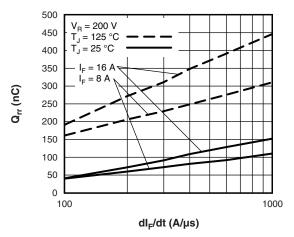
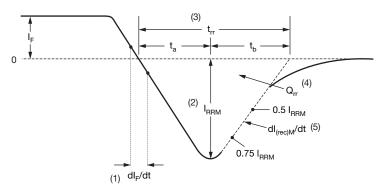


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (\text{Pd} + \text{Pd}_{\text{REV}}) \times R_{\text{th,JC}}; \\ \text{Pd} & = \text{Forward power loss} = I_{\text{F(AV)}} \times V_{\text{FM}} \text{ at } (I_{\text{F(AV)}}/D) \text{ (see fig. 6)}; \\ \text{Pd}_{\text{REV}} & = \text{Inverse power loss} = V_{\text{R1}} \times I_{\text{R}} \text{ (1 - D)}; I_{\text{R}} \text{ at } V_{\text{R1}} = \text{Rated } V_{\text{R}} \\ \end{array}$ 



- (1) dl<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{rr}$  area under curve defined by  $\mathbf{t}_{rr}$  and  $\mathbf{I}_{\mathrm{RRM}}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5)  $dI_{(rec)M}/dt$  - peak rate of change of current during  $t_{b}$  portion of  $t_{rr}$ 

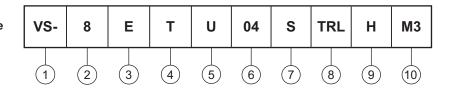
Fig. 9 - Reverse Recovery Waveform and Definitions

## VS-8ETU04SHM3, VS-8ETU04-1HM3

Vishay Semiconductors

#### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - Current rating (8 A)

E = single diode

T = TO-220, D<sup>2</sup>PAK

5 - U = ultrafast recovery

Voltage rating (04 = 400 V)

7 - • S = D<sup>2</sup>PAK

• -1 = TO-262

None = tube (50 pieces)

• TRL = tape and reel (left oriented, for D2PAK package)

• TRR = tape and reel (right oriented, for D<sup>2</sup>PAK package)

9 - H = AEC-Q101 qualified

- M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-8ETU04SHM3	50	1000	Antistatic plastic tube					
VS-8ETU04STRRHM3	800	800	13"diameter reel					
VS-8ETU04STRLHM3	800	800	13"diameter plastic reel					
VS-8ETU04-1HM3	50	1000	Antistatic plastic tube					

LINKS TO RELATED DOCUMENTS						
Dimensions	TO-263AB (D <sup>2</sup> PAK)	www.vishay.com/doc?95046				
Differisions	TO-262AA	www.vishay.com/doc?95419				
Part marking information	TO-263AB (D <sup>2</sup> PAK)	www.vishay.com/doc?95444				
Part marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information	TO-263AB (D <sup>2</sup> PAK)	www.vishay.com/doc?95032				



## D<sup>2</sup>PAK

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES	TES SYMBOL	MILLIM	ETERS	INC	HES	NOTES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	) BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

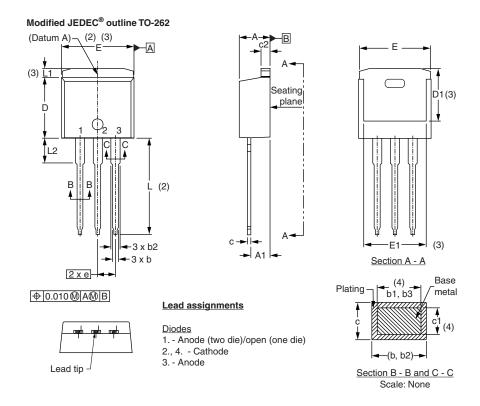
#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



## **TO-262**

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.10	D BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

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Vishay

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